



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20170109001
Datasheet for THS4551
Change Notification**

Date: January 27, 2017
To: PREMIER FARNELL PCN

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20170109001
Data Sheet Change Notification
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE
THS4551IDGKT

CUSTOMER PART NUMBER
null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20170109001	PCN Date:	Jan. 27, 2017
Title:	Datasheet for THS4551		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Apr. 27, 2017		
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

Notification Details

Description of Change:

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



THS4551

SBOS778B –APRIL 2016–REVISED NOVEMBER 2016

Changes from Revision A (August 2016) to Revision B

Page

• Changed I_Q value in THS4551 row of <i>Device Family Comparison</i>	4
• Added second row and footnote 2 to <i>Voltage</i> parameter of <i>Absolute Maximum Ratings</i> table	5
• Added package differences and footnote 3 to <i>ESD Ratings</i> table	5
• Changed footnotes 1 and 2 in <i>5-V Electrical Characteristics</i> table	6
• Added test conditions to A_{OL} parameter in <i>5-V Electrical Characteristics</i> table	7
• Changed <i>Input offset voltage drift</i> parameter	7
• Changed I_{IB} parameter minimum and maximum specifications in last three rows	7
• Changed <i>Input bias current drift</i> parameter test conditions and specifications	7
• Added <i>Input offset current drift</i> parameter test conditions, minimum and maximum specifications, and test level value to second row	7
• Changed test conditions of <i>Common-mode input, low</i> and <i>Common-mode input, high</i> parameters	7
• Changed test conditions of <i>Continuous output current</i> and <i>Linear output current</i> parameters	8
• Changed test conditions of <i>Enable voltage threshold</i> and <i>Disable voltage threshold</i> parameters	8
• Changed specifications of <i>Power-down quiescent current</i> parameter	8
• Changed <i>Common-mode loop supply headroom to negative supply</i> parameter test conditions	9
• Changed test conditions and maximum specifications of <i>Common-mode loop supply headroom to positive supply</i> parameter	9
• Added test conditions to DC Performance, A_{OL} parameter	10
• Changed <i>Input offset voltage drift</i> parameter test conditions in first row, added second row	10
• Changed minimum and maximum specifications in last three rows of I_{IB} parameter	10

• Changed <i>Input bias current drift</i> parameter test conditions.....	10
• Added second row to <i>Input offset current drift</i> parameter	10
• Changed test conditions of <i>Common-mode input, low</i> and <i>Common-mode input, high</i> parameters.....	10
• Changed test conditions of <i>Continuous output current</i> and <i>Linear output current</i> parameters	11
• Changed test conditions of <i>Enable voltage threshold</i> and <i>Disable voltage threshold</i> parameters	11
• Changed $I_{Q(PD)}$ parameter specifications	11
• Changed <i>Common-mode loop supply headroom to negative supply</i> parameter test conditions.....	12
• Changed <i>Common-mode loop supply headroom to positive supply</i> parameter test conditions and maximum specifications	12
• Changed conditions of Figure 49 to Figure 54	21
• Changed <i>Single-Ended Source</i> to a <i>Differential Gain of a 1-V/V Test Circuit</i> figure	23
• Changed main <i>Device Functional Modes</i> section: changed value of \overline{PD} pin voltage	38
• Changed the minimum value for single-supply operation in the <i>Operating the Power Shutdown Feature</i> section	45
• Added SBOS476, SBOC466, SBOC463, SBOC467, SBOS460, SBOC477, SBOC472, SLOC341, SBOC469, SBOC462, SBOC461, SBOC465, SBOC464, SBOC475, SBOC474, SBOC471, SBOC459, SBOC470, SBOC468, and SBOC473 to <i>Related Documentation</i> section	62

The datasheet number will be changing.

Device Family	Change From:	Change To:
THS4551	SBOS778A	SBOS778B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/THS4551>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

THS4551IDGKR	THS4551IDGKT	THS4551IRGTR	THS4551IRGTT		
THS4551IRUNR	THS4551IRUNT				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com